

### APPLICATIONS

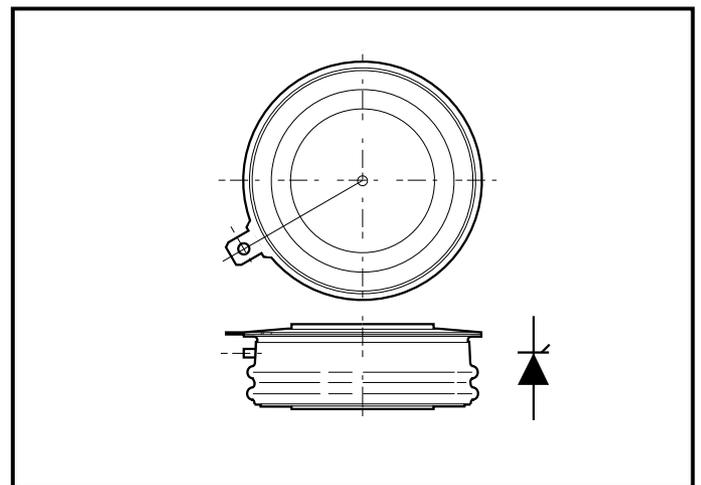
- Variable speed A.C. motor drive inverters (VSD-AC)
- Uninterruptable Power Supplies
- High Voltage Converters
- Choppers
- Welding
- Induction Heating
- DC/DC Converters

### KEY PARAMETERS

$I_{TCM}$	700A
$V_{DRM}$	1300V
$I_{T(AV)}$	250A
$dV_D/dt$	500V/ $\mu$ s
$di_T/dt$	500A/ $\mu$ s

### FEATURES

- Double Side Cooling
- High Reliability In Service
- High Voltage Capability
- Fault Protection Without Fuses
- High Surge Current Capability
- Turn-off Capability Allows Reduction In Equipment Size And Weight. Low Noise Emission Reduces Acoustic Cladding Necessary For Environmental Requirements



Outline type code: E.  
See Package Details for further information.

### VOLTAGE RATINGS

Type Number	Repetitive Peak Off-state Voltage $V_{DRM}$	Repetitive Peak Reverse Voltage $V_{RRM}$	Conditions
DGT304SE13	1300	16	$T_{vj} = 125^\circ\text{C}$ , $I_{DM} = 50\text{mA}$ , $I_{RRM} = 50\text{mA}$ , $V_{RG} = 2\text{V}$

### CURRENT RATINGS

Symbol	Parameter	Conditions	Max.	Units
$I_{TCM}$	Repetitive peak controllable on-state current	$V_D = 60\%V_{DRM}$ , $T_j = 125^\circ\text{C}$ , $di_{GQ}/dt = 15\text{A}/\mu\text{s}$ , $C_s = 2.0\mu\text{F}$	700	A
$I_{T(AV)}$	Mean on-state current	$T_{HS} = 80^\circ\text{C}$ . Double side cooled. Half sine 50Hz.	250	A
$I_{T(RMS)}$	RMS on-state current	$T_{HS} = 80^\circ\text{C}$ . Double side cooled. Half sine 50Hz.	390	A

## SURGE RATINGS

Symbol	Parameter	Conditions	Max.	Units
$I_{TSM}$	Surge (non-repetitive) on-state current	10ms half sine. $T_j = 125^\circ\text{C}$	4.0	kA
$I^2t$	$I^2t$ for fusing	10ms half sine. $T_j = 125^\circ\text{C}$	80000	$\text{A}^2\text{s}$
$di_T/dt$	Critical rate of rise of on-state current	$V_D = 60\% V_{DRM}$ , $I_T = 700\text{A}$ , $T_j = 125^\circ\text{C}$ , $I_{FG} > 20\text{A}$ , Rise time $< 1.0\mu\text{s}$	500	$\text{A}/\mu\text{s}$
$dV_D/dt$	Rate of rise of off-state voltage	To $80\% V_{DRM}$ ; $R_{GK} \leq 1.5\Omega$ , $T_j = 125^\circ\text{C}$	500	$\text{V}/\mu\text{s}$

## GATE RATINGS

Symbol	Parameter	Conditions	Min.	Max.	Units
$V_{RGM}$	Peak reverse gate voltage	This value maybe exceeded during turn-off	-	16	V
$I_{FGM}$	Peak forward gate current		-	50	A
$P_{FG(AV)}$	Average forward gate power		-	10	W
$P_{RGM}$	Peak reverse gate power		-	6	kW
$di_{GQ}/dt$	Rate of rise of reverse gate current		10	50	$\text{A}/\mu\text{s}$
$t_{ON(min)}$	Minimum permissible on time		20	-	$\mu\text{s}$
$t_{OFF(min)}$	Minimum permissible off time		40	-	$\mu\text{s}$

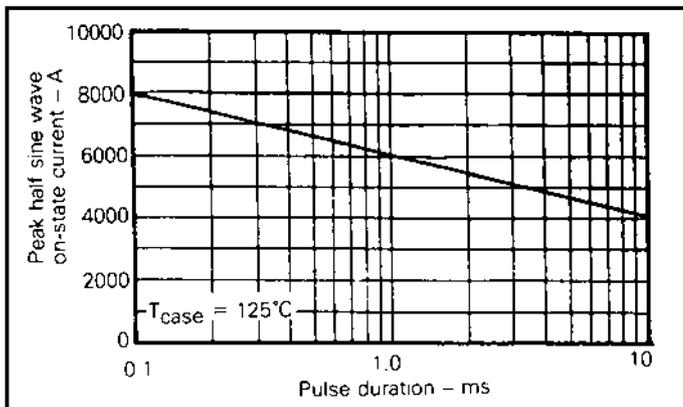
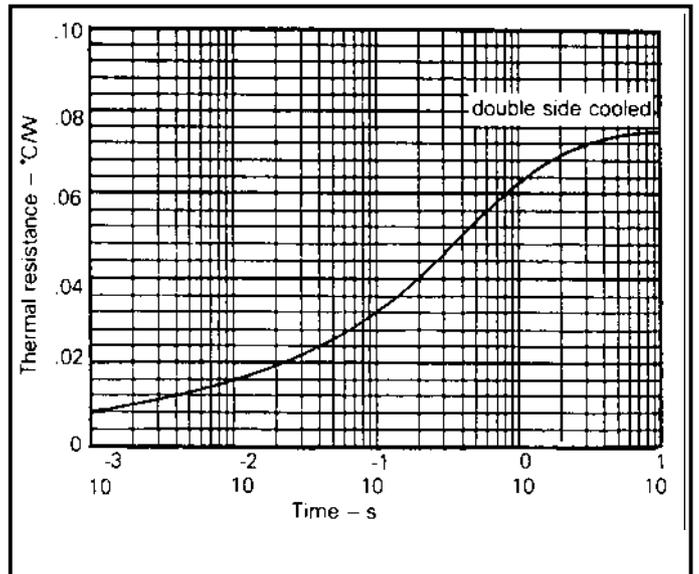
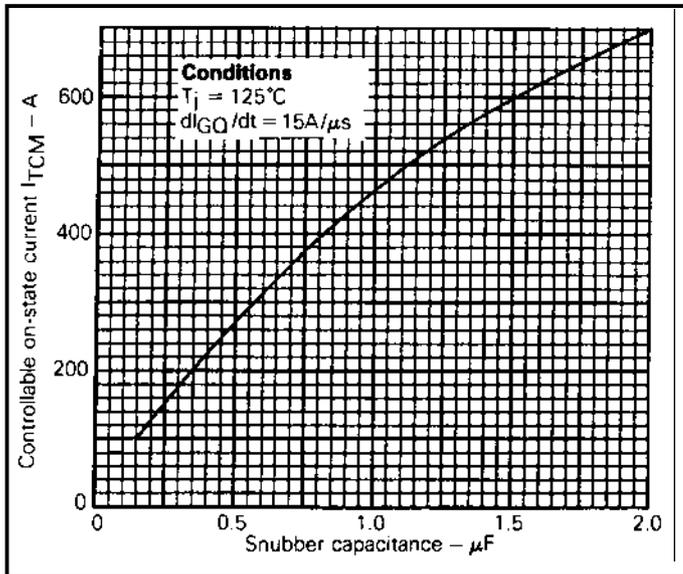
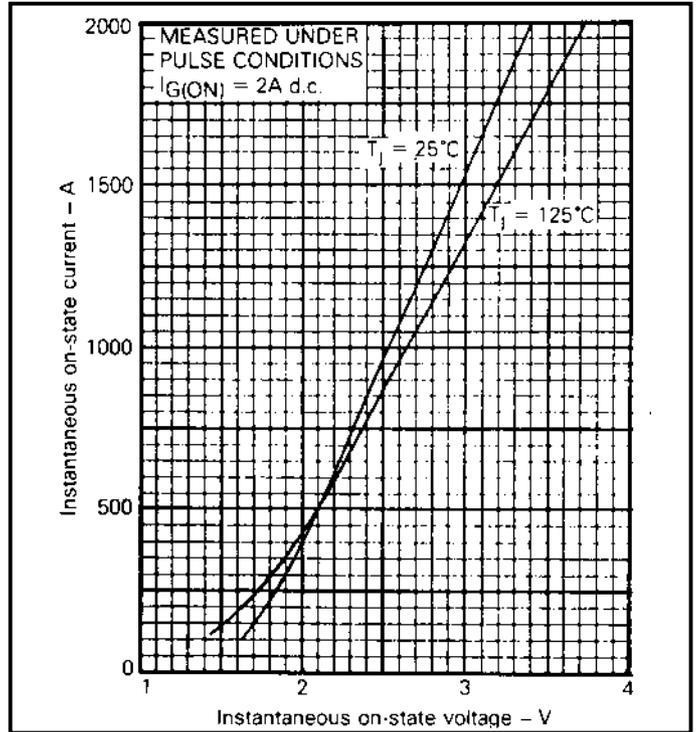
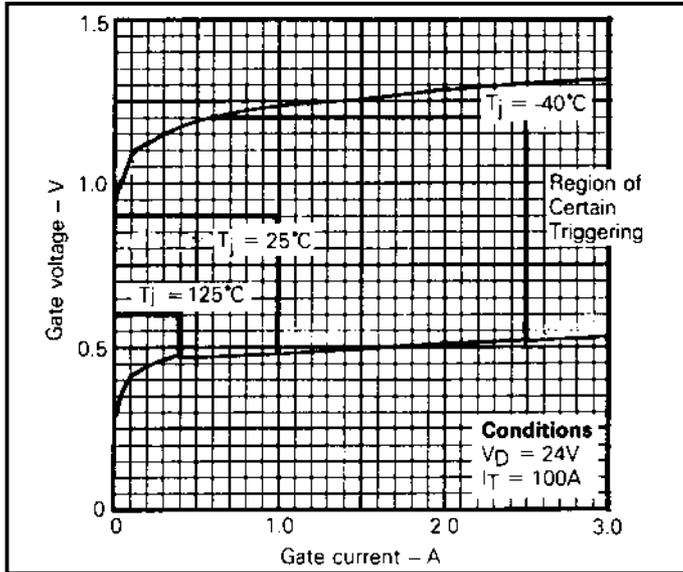
## THERMAL RATINGS

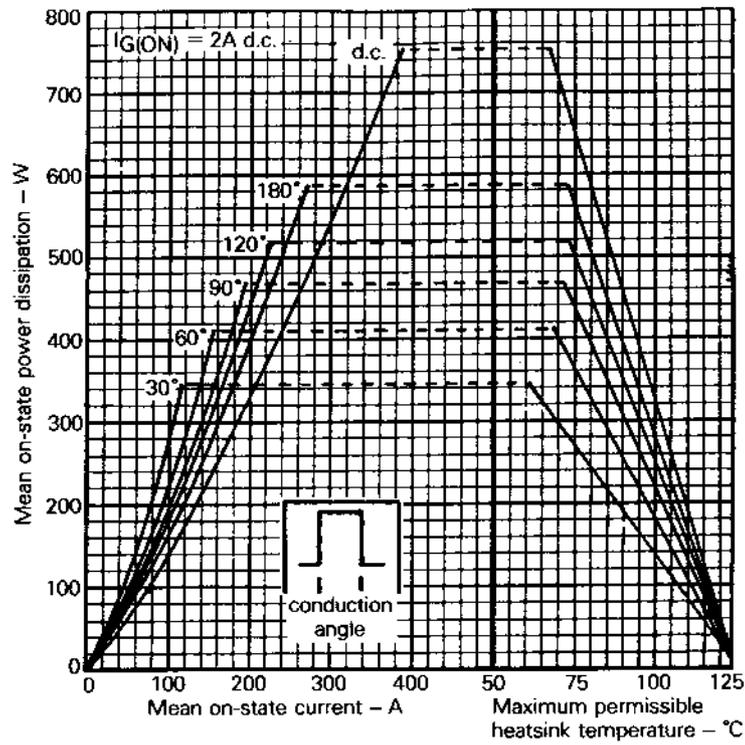
Symbol	Parameter	Conditions	Min.	Max.	Units	
$R_{th(j-hs)}$	DC thermal resistance - junction to heatsink surface	Double side cooled	-	0.075	$^\circ\text{C}/\text{W}$	
		Anode side cooled	-	0.12	$^\circ\text{C}/\text{W}$	
		Cathode side cooled	-	0.20	$^\circ\text{C}/\text{W}$	
$R_{th(c-hs)}$	Contact thermal resistance	Clamping force 5.5kN With mounting compound	per contact	-	0.018	$^\circ\text{C}/\text{W}$
$T_{vj}$	Virtual junction temperature		-	125	$^\circ\text{C}$	
$T_{OP}/T_{stg}$	Operating junction/storage temperature range		-40	125	$^\circ\text{C}$	
-	Clamping force		5.0	6.0	kN	

**CHARACTERISTICS**

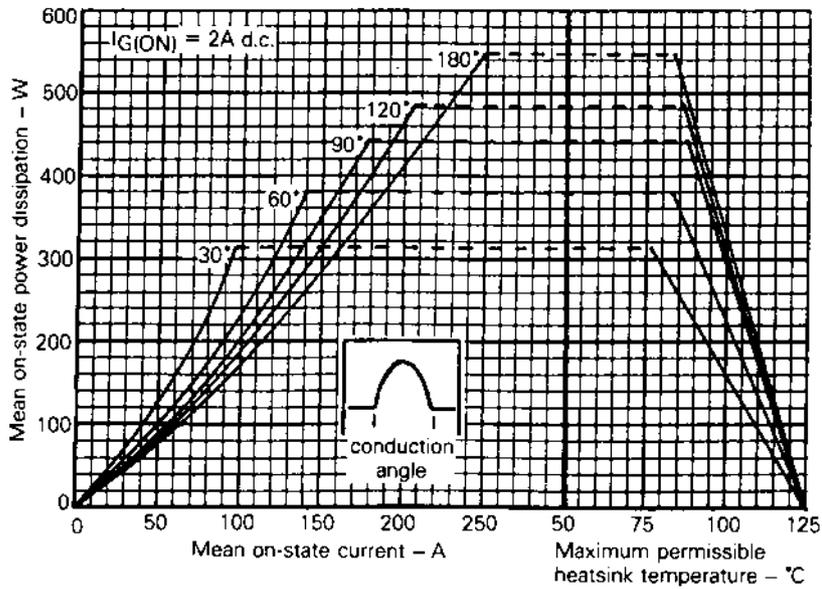
<b>T<sub>j</sub> = 125°C unless stated otherwise</b>					
<b>Symbol</b>	<b>Parameter</b>	<b>Conditions</b>	<b>Min.</b>	<b>Max.</b>	<b>Units</b>
V <sub>TM</sub>	On-state voltage	At 600A peak, I <sub>G(ON)</sub> = 2A d.c.	-	2.2	V
I <sub>DM</sub>	Peak off-state current	At V <sub>DRM</sub> , V <sub>RG</sub> = 2V	-	25	mA
I <sub>RRM</sub>	Peak reverse current	At V <sub>RRM</sub>	-	50	mA
V <sub>GT</sub>	Gate trigger voltage	V <sub>D</sub> = 24V, I <sub>T</sub> = 100A, T <sub>j</sub> = 25°C	-	0.9	V
I <sub>GT</sub>	Gate trigger current	V <sub>D</sub> = 24V, I <sub>T</sub> = 100A, T <sub>j</sub> = 25°C	-	1.0	A
I <sub>RGM</sub>	Reverse gate cathode current	V <sub>RGM</sub> = 16V, No gate/cathode resistor	-	50	mA
E <sub>ON</sub>	Turn-on energy	V <sub>D</sub> = 900V, I <sub>T</sub> = 600A, di <sub>T</sub> /dt = 300A/μs	-	130	mJ
t <sub>d</sub>	Delay time	I <sub>FG</sub> = 20A, rise time < 1.0μs	-	1.5	μs
t <sub>r</sub>	Rise time	R <sub>L</sub> = (Residual inductance 3μH)	-	3.0	μs
E <sub>OFF</sub>	Turn-off energy	I <sub>T</sub> = 600A, V <sub>DM</sub> = 750V Snubber Cap Cs = 1.5μF, di <sub>GQ</sub> /dt = 15A/μs R <sub>L</sub> = (Residual inductance 3μH)	-	350	mJ
t <sub>tail</sub>	Tail time		-	10	μs
t <sub>gs</sub>	Storage time		-	11	μs
t <sub>gf</sub>	Fall time		-	0.9	μs
t <sub>gq</sub>	Gate controlled turn-off time		-	11.9	μs
Q <sub>GQ</sub>	Turn-off gate charge		-	700	μC
Q <sub>GQT</sub>	Total turn-off gate charge		-	1400	μC

CURVES





**Fig.6 Steady state rectangular wave conduction loss - double side cooled**



**Fig.7 Steady state sinusoidal wave conduction loss - double side cooled**

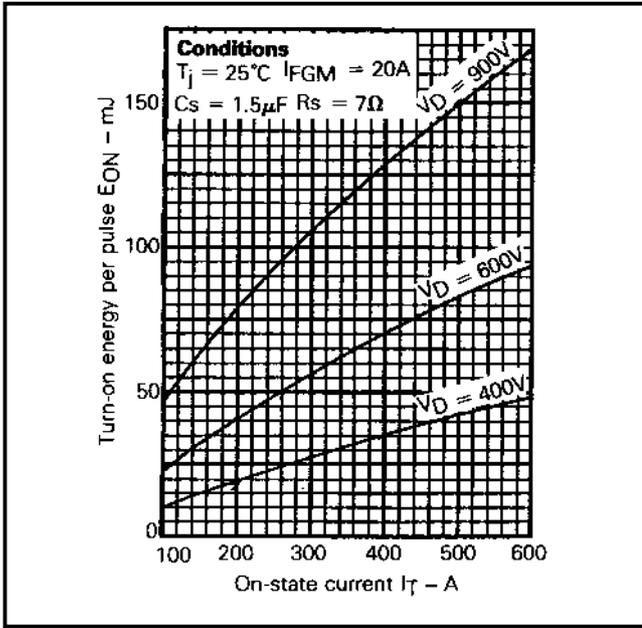


Fig.8 Turn-on energy vs on-state current

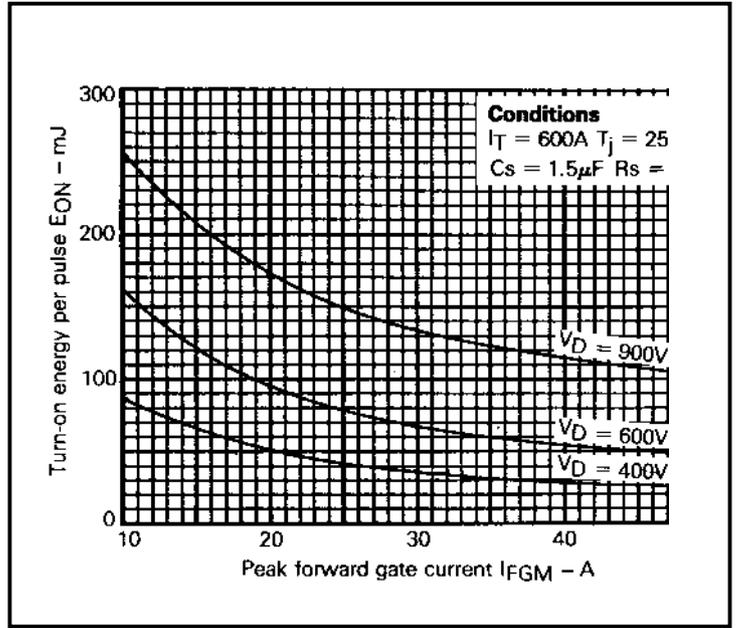


Fig.9 Turn-on energy vs peak forward gate current

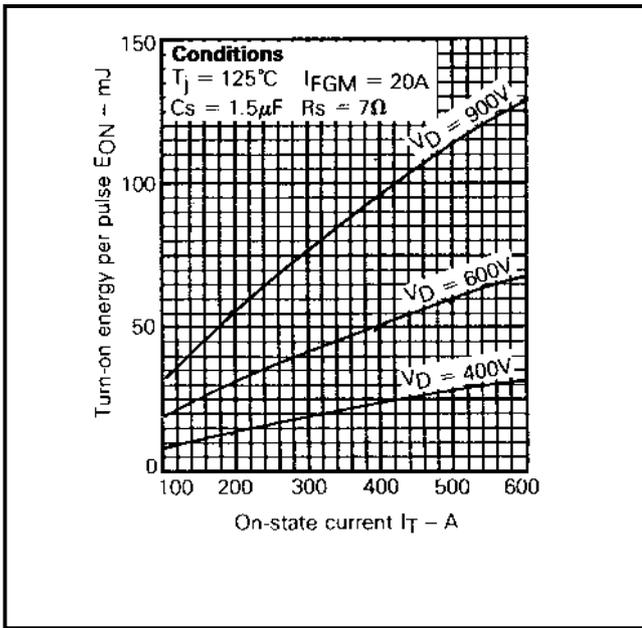


Fig.10 Turn-on energy vs on-state current

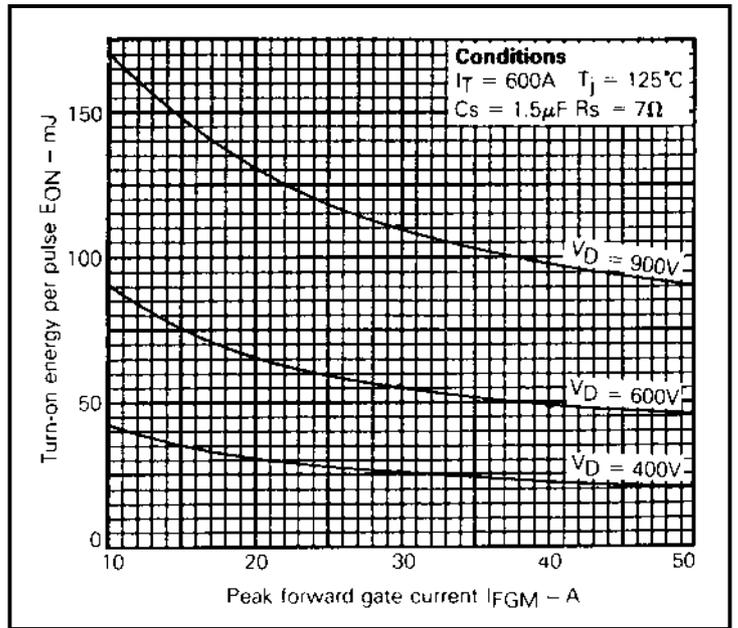
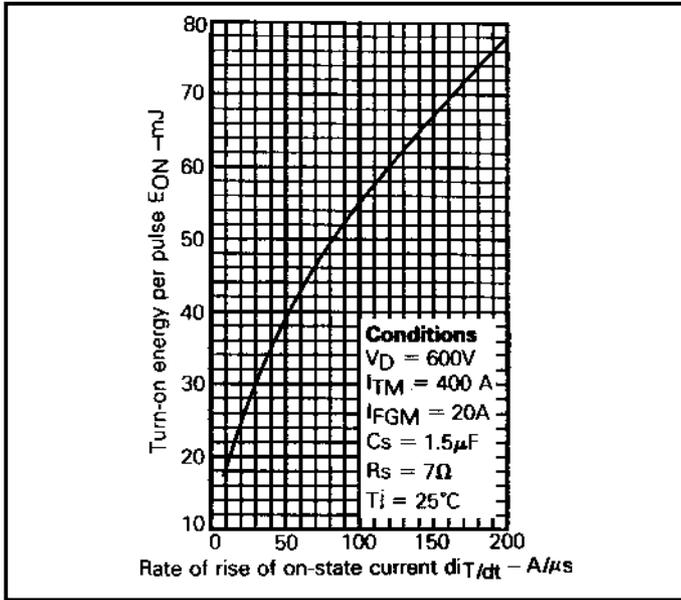
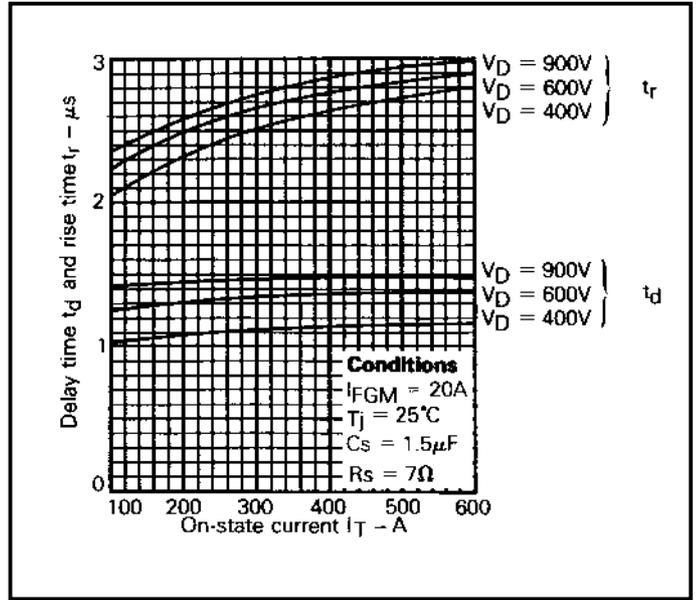


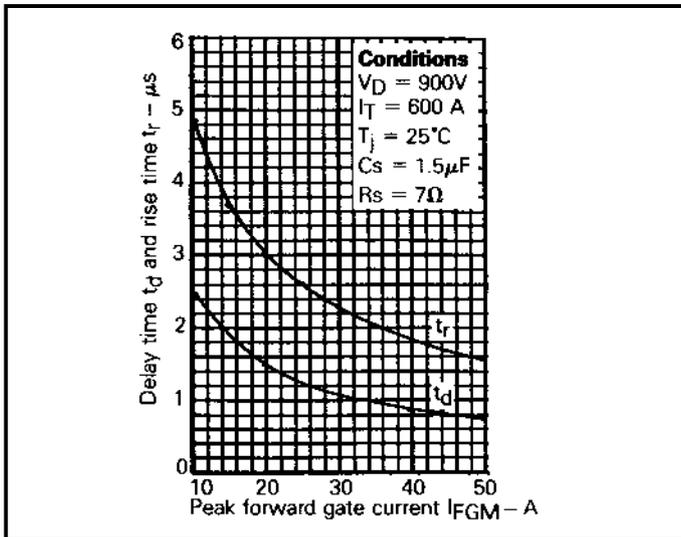
Fig.11 Turn-on energy vs peak forward gate current



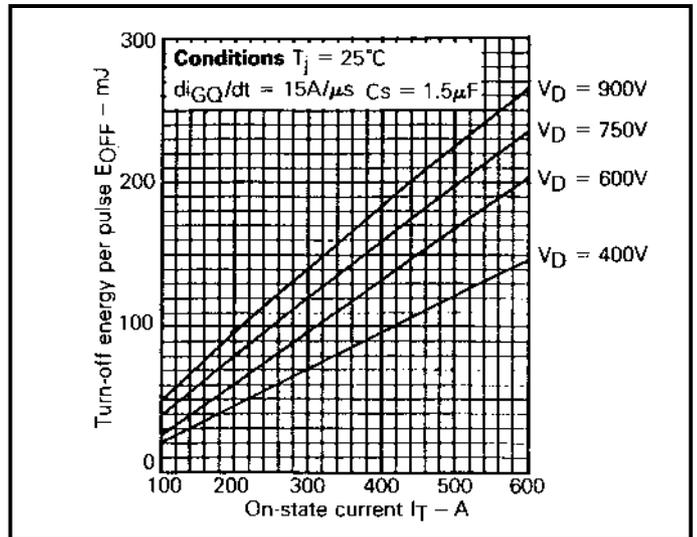
**Fig.12 Turn-on energy vs rate of rise of on-state current**



**Fig.13 Delay time and rise time vs on-state current**



**Fig.14 Delay time and rise time vs peak forward gate current**



**Fig.15 Turn-off energy vs on-state current**

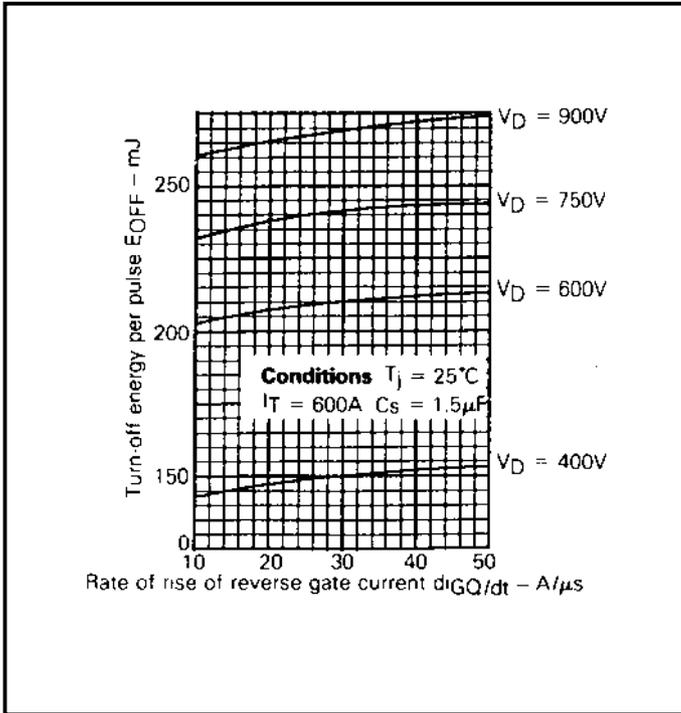


Fig.16 Turn-off energy vs rate of rise of reverse gate current

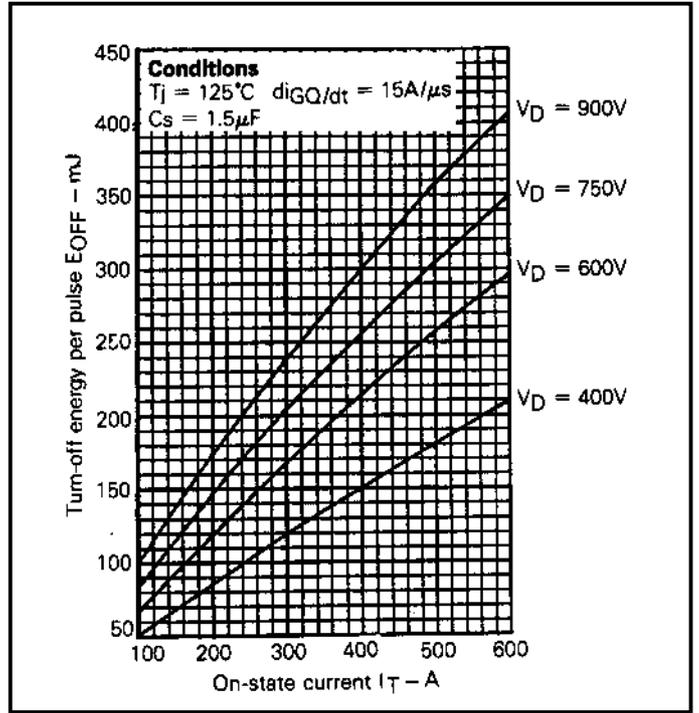


Fig.17 Turn-off energy vs on-state current

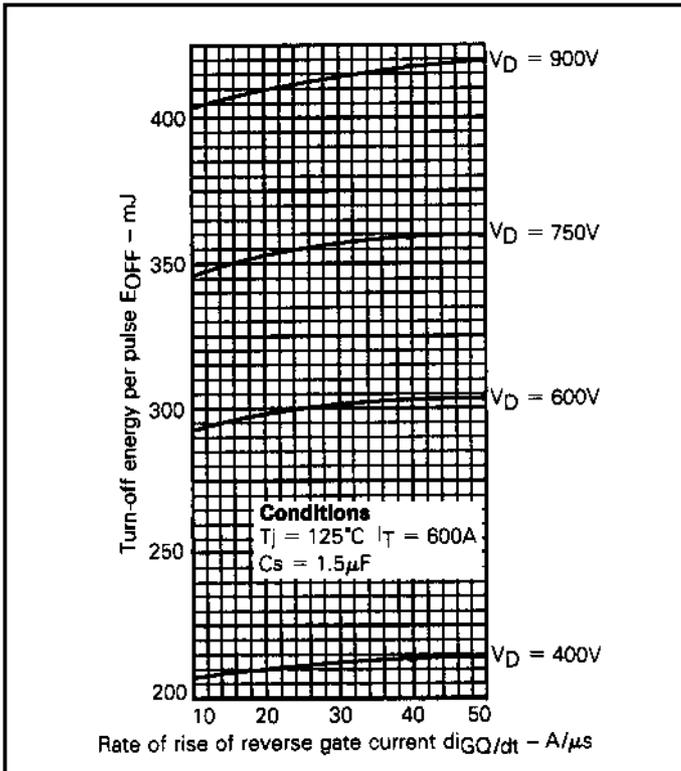


Fig.18 Turn-off energy vs rate of rise of reverse gate current

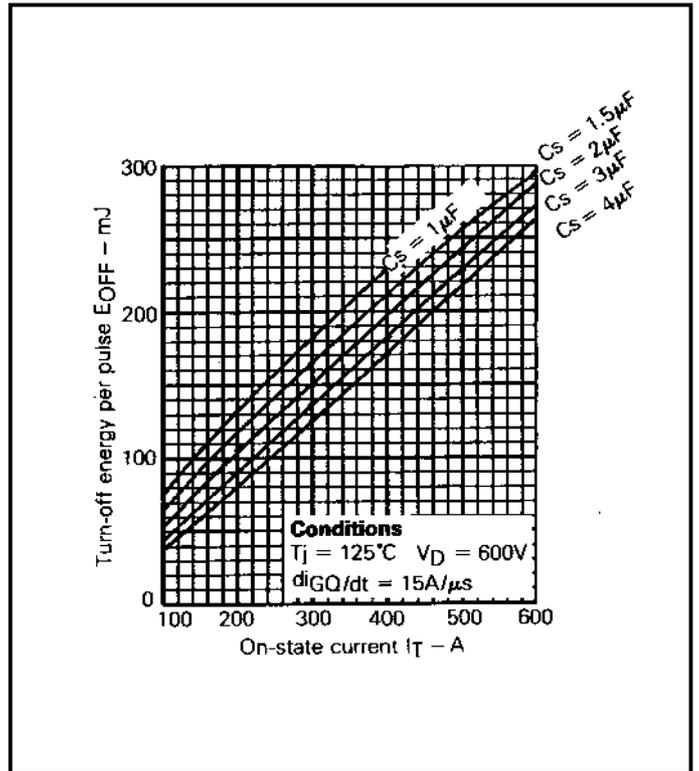
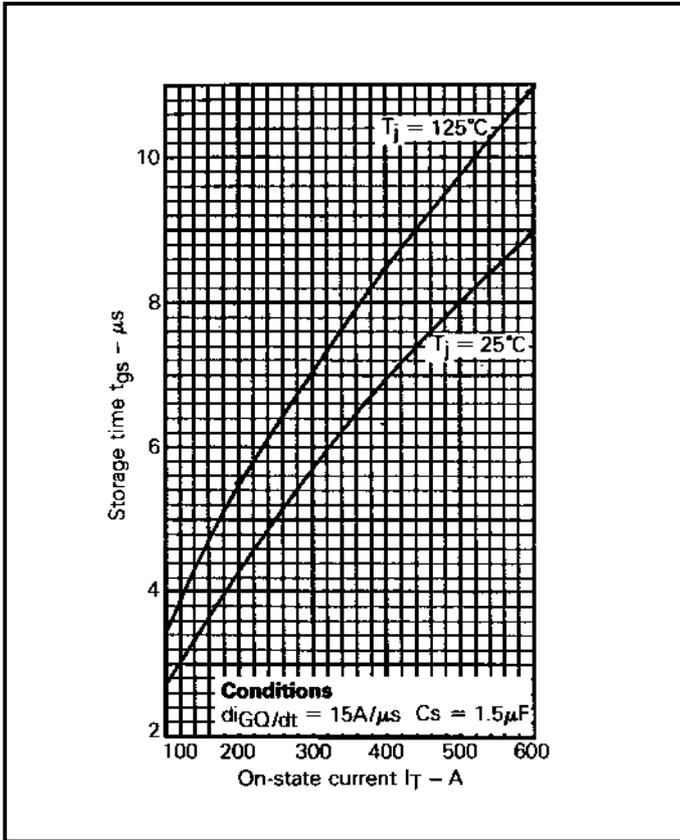
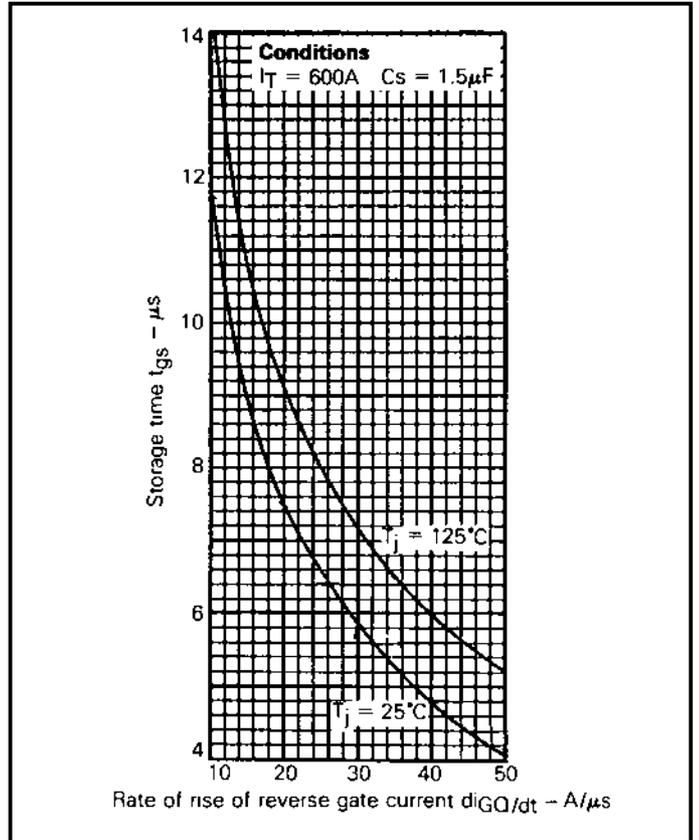


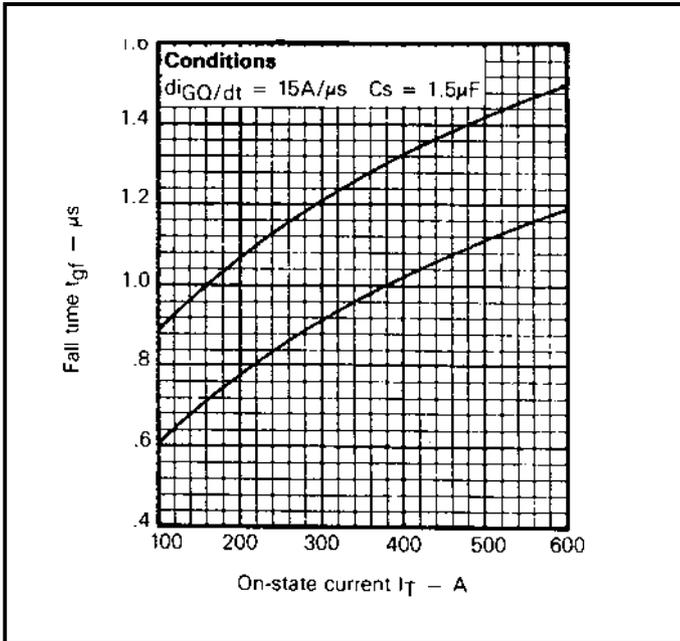
Fig.19 Turn-off energy vs on-state current with  $C_s$  as parameter



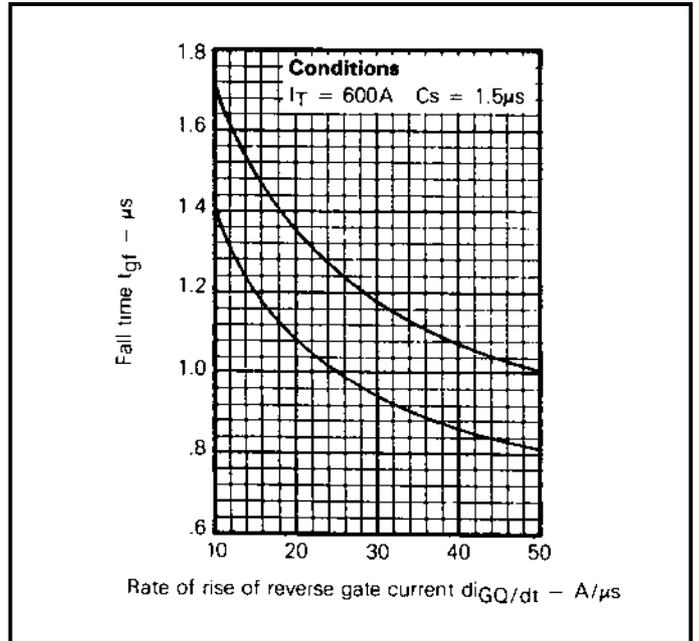
**Fig.20 Storage time vs on-state current**



**Fig.21 Storage time vs rate of rise of reverse gate current**



**Fig.22 Fall time vs on-state current**



**Fig.23 Fall time vs rate of rise of reverse gate current**

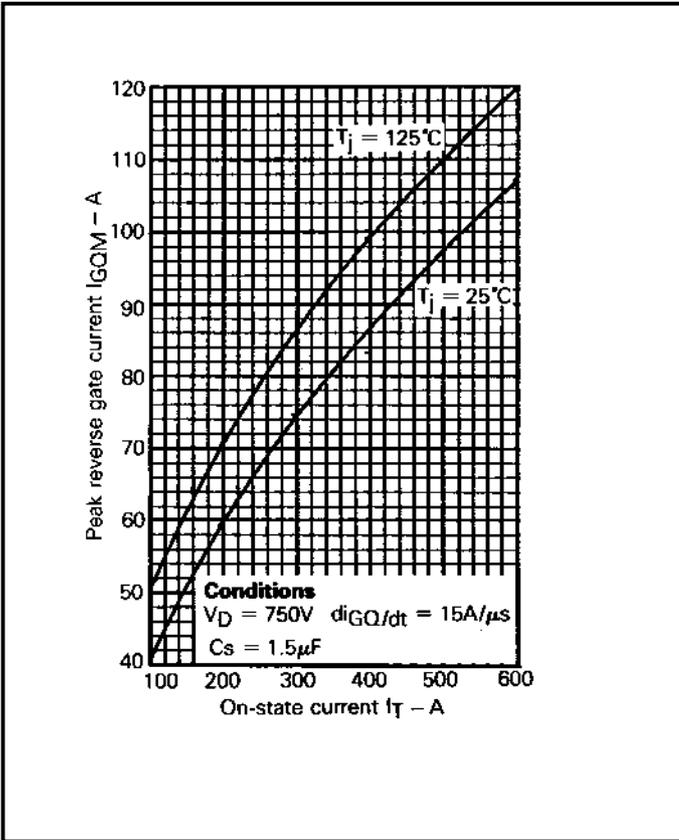


Fig.24 Peak reverse gate current vs on-state current

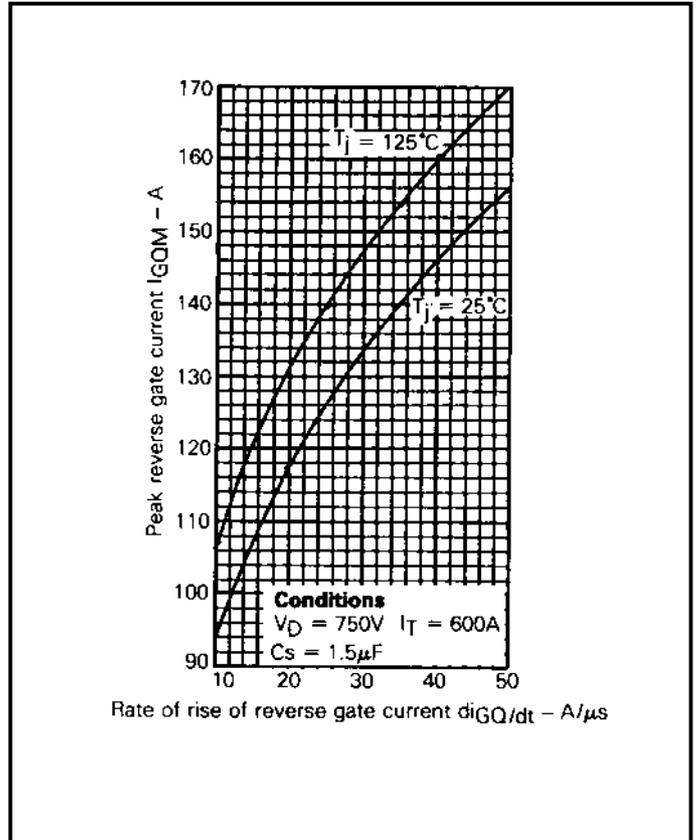


Fig.25 Peak reverse gate current vs rate of rise of reverse gate current

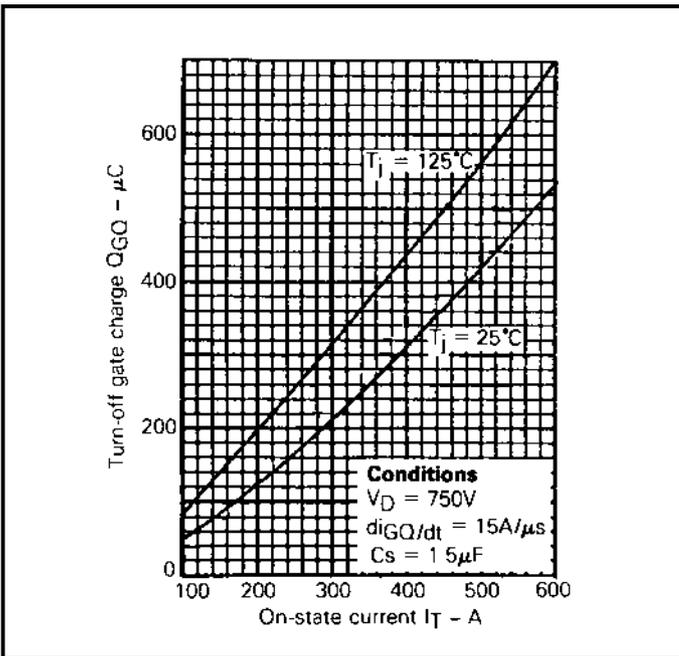


Fig.26 Turn-off gate charge vs on-state current

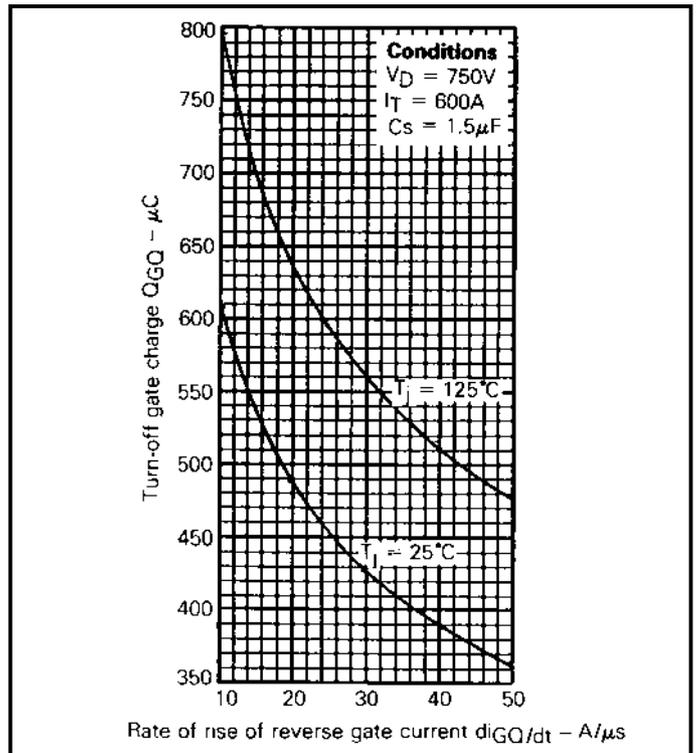


Fig.27 Turn-off gate charge vs rate of rise of reverse gate current

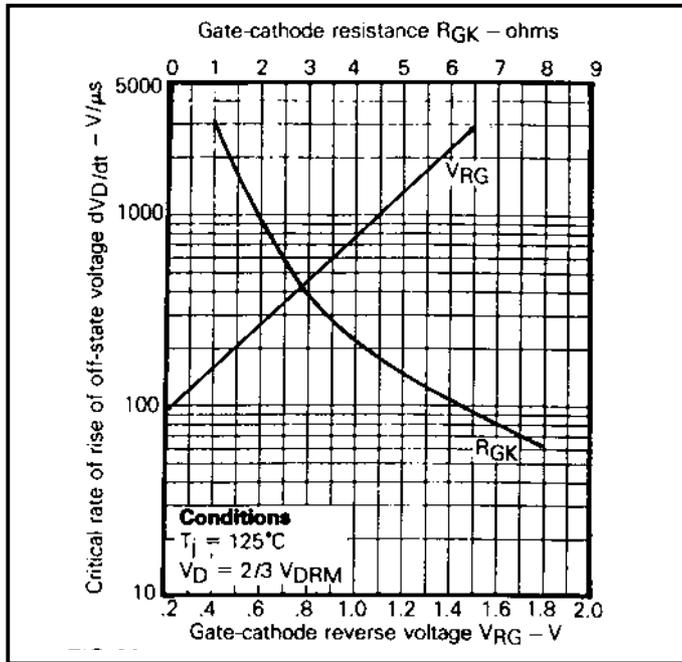


Fig.28 Dependence of critical  $dV_D/dt$  on gate-cathode resistance and gate-cathode reverse voltage

Snubber Capacitor $C_s$ ( $\mu\text{F}$ )	Snubber Resistor $R_s$ ( $\Omega$ )	Minimum Reset Time ( $\mu\text{s}$ )
2	7	35
	5	30
1.5	7	26
	5	22
1	7	17
	5	15

Table of snubber discharge time variation with snubber capacitor value.

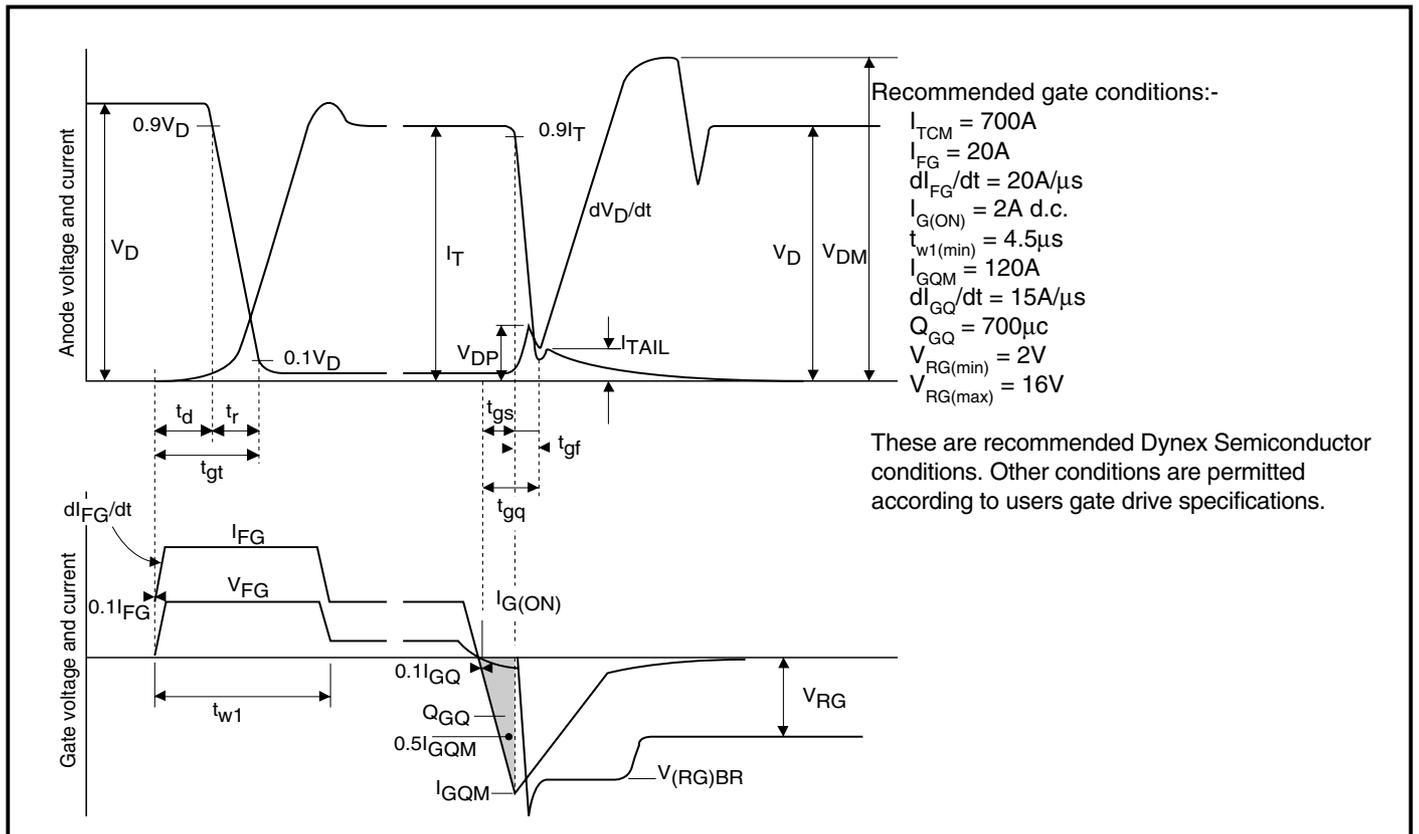
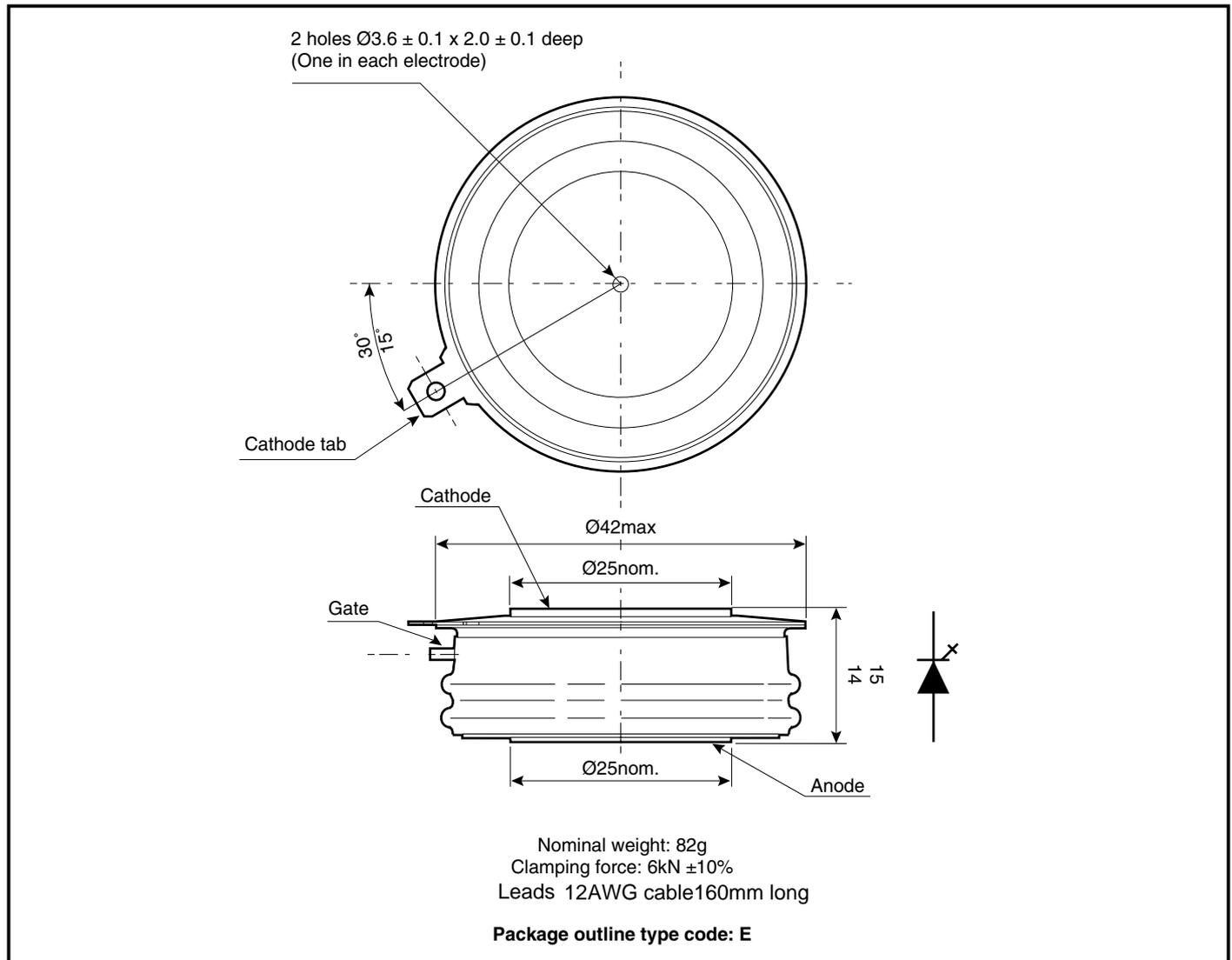


Fig.29 General switching waveforms

These are recommended Dynex Semiconductor conditions. Other conditions are permitted according to users gate drive specifications.

## PACKAGE DETAILS

For further package information, please contact Customer Services. All dimensions in mm, unless stated otherwise.  
DO NOT SCALE.





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The products must not be touched when operating because there is a danger of electrocution or severe burning. Always use protective safety equipment such as appropriate shields for the product and wear safety glasses. Even when disconnected any electric charge remaining in the product must be discharged and allowed to cool before safe handling using protective gloves.

Extended exposure to conditions outside the product ratings may affect reliability leading to premature product failure. Use outside the product ratings is likely to cause permanent damage to the product. In extreme conditions, as with all semiconductors, this may include potentially hazardous rupture, a large current to flow or high voltage arcing, resulting in fire or explosion. Appropriate application design and safety precautions should always be followed to protect persons and property.

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<b>Target Information:</b>	This is the most tentative form of information and represents a very preliminary specification. No actual design work on the product has been started.
<b>Preliminary Information:</b>	The product design is complete and final characterisation for volume production is in progress. The datasheet represents the product as it is now understood but details may change.
<b>No Annotation:</b>	The product has been approved for production and unless otherwise notified by Dynex any product ordered will be supplied to the <b>current version of the data sheet prevailing at the time of our order acknowledgement.</b>

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